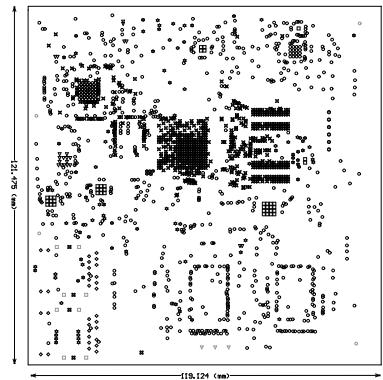
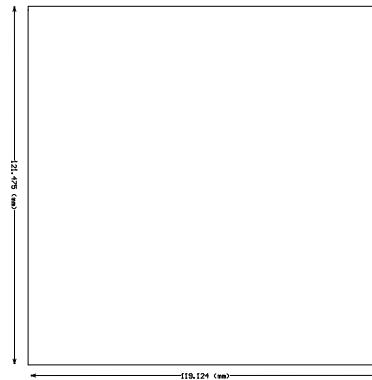
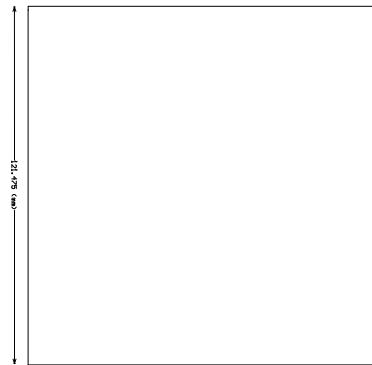
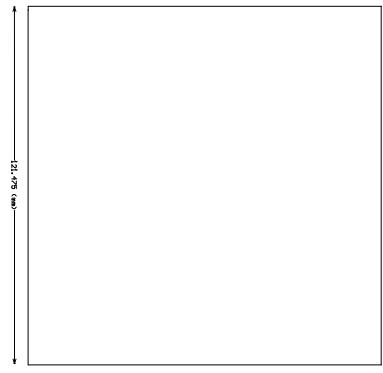


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- LEAD OFF DISTANCE OF BOARD SHALL NOT EXCEED .10 INCH PER INCH.
- SILKSCREEN COMPONENT SITES (TOP AND BOTTOM) USING BLUE NON-CONDUCTIVE INK. SILKSCREEN TO BE CRISP AND LEGIBLE. DO NOT CLIP SILKSCREEN OVER MASKED VIAS.
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- BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0. VENDOR'S UL LOGO OR DESIGNATION SHALL BE LOCATED ON SOLDEN SIDE OF BOARD.
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Symbol Hit Count Finished Hole Size Plated Hole Type

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▼	4	118.11mil (.3.00mm)	PTH	Round
○	5	95.14mil (.2.41mm)	PTH	Round
■	6	42.12mil (.1.07mm)	PTH	Round
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○	32	.016mil (.020mm)	PTH	Round
○	41	12.98mil (.0.30mm)	PTH	Round
■	103	18.64mil (.0.47mm)	PTH	Round
□	778	3.94mil (.0.10mm)	PTH	Round
○	898	7.67mil (.0.200mm)	PTH	Round
1940 Total				

1940 Total

(19.124 mm)

(12.721 mm)

Layer Stack Up Detail for: WhiteRHINO\_0.1.PcbDoc

Layer	Material	Thickness	Dielectric	Material	Thickness	Dielectric
Top Solder Mask	(.075)	0.010mm				
L1_Top Layer	(.075)	0.010mm				
L2_GND	(.075)	0.010mm				
L3_Critical	(.075)	0.010mm				
L4_Critical	(.075)	0.010mm				
L5_GND	(.075)	0.010mm				
L6_Power	(.075)	0.010mm				
L7_Non-Critical	(.075)	0.010mm				
L8_Power	(.075)	0.010mm				
L9_Critical	(.075)	0.010mm				
L10_Critical	(.075)	0.010mm				
L11_GND	(.075)	0.010mm				
L12_Bottom Layer	(.075)	0.010mm				
Bottom Solder Mask	(.075)	0.010mm				
			Solder Resist			
			3.50			

(19.124 mm)

(12.721 mm)

Name: Sijmen Hazarka Radar And Remote Sensing Group University of Cape Town	Name: DUJNAV HAZARKA Radar And Remote Sensing Group University of Cape Town	Title: White RHINO 0.1 University of Cape Town
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